Product Change Notification

Change Notification #:	**115108 - 00**
Change Title:	**Select Intel® SSD DC P3500 Series, Intel® SSD DC P3600 Series, Intel® SSD DC P3700 Series Products, PCN 115108-00, Transport Media, Packaging Update**
Date of Publication:	**December 01, 2016**

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	December 16, 2016

Description of Change to the Customer:

The Intel® SSD DC P3500 Series, Intel® SSD DC P3600 Series, and Intel® SSD DC P3700 Series Products listed in the tables and images below will have the following change:

- The current package kit contains 10x Add-In-Card (AIC) units which are placed inside a single 10 unit tray. The carton box used in this package is: 363X243X166MM.
- The new package kit contains 10x units inside single clamshell packs which are placed inside a new carton box. Carton Box: 251X226X164MM.

See images and Products Affected Table below.

Current Packaging Kit:

10x Add-In-Card units in one black tray

Carton Box:363X243X166MM
Carton Weight: ~3101g

New Packaging Kit:

10x single Clamshell pack
Wrapped by foam

Carton Box: 251X226X164MM
Carton Weight: ~2752g

Single Clamshell pack

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD DC P3700 Series (400GB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDMD400G410	937364
Intel® SSD DC P3700 Series (800GB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDMD800G410	937365
Intel® SSD DC P3700 Series (1.6TB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDMD016T410	937366
Intel® SSD DC P3700 Series (2.0TB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDMD020T410	937367
Intel® SSD DC P3600 Series (400GB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDME400G410	937374
Intel® SSD DC P3600 Series (800GB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDME800G410	937375
Intel® SSD DC P3600 Series (1.2TB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDME012T410	937376
Intel® SSD DC P3600 Series (1.6TB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDME016T410	937377
Intel® SSD DC P3600 Series (2.0TB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDME020T410	937378
Intel® SSD DC P3500 Series (400GB, 1/2 Height PCIe 3.0 x4, 20nm, MLC) Generic 10 Pack	SSDPEDMX400G410	939934

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the packaging used for shipping.

Customers should be aware of the changes to the packaging and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material from either the factory or the distribution center, however there is still a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
December 01, 2016	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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